

Electronic Patent Application Fee Transmittal

Application Number:	10721382
Filing Date:	26-Nov-2003
Title of Invention:	High density chip scale leadframe package and method of manufacturing the package
First Named Inventor/Applicant Name:	Hien Boon Tan
Filer:	Carl Joseph Pellegrini/ruth swanson
Attorney Docket Number:	Q78432

Filed as Large Entity

Utility under 35 USC 111(a) Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Patent-Appeals-and-Interference:

Notice of appeal	1401	1	540	540
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Post-Allowance-and-Post-Issuance:

Extension-of-Time:				
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Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 1 month with \$0 paid	1251	1	130	130
Miscellaneous:				
Total in USD (\$)				670